

Data sheet Product ICK S R 28,5 x 12,5



Heatsinks and active heatsinks for processors>Pin heatsinks

Ø 28,5 x 12.5 mm, pin heatsinks round

Features

design:	round
way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
diameter:	28.5 mm
height:	12.5 mm
plate thickness:	3 mm
weight:	5.7 g
thermal resistance:	10.3 - 2.3 K/W
dissipation loss:	5.83 W
surface:	Al-natural

Technical Drawing

